

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ICE2A265	**Issued**	29. August 2013
MA#	MA001051778		
Package	PG-DIP-8-9	**Weight***	518.64 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.932	0.95	0.95	9510	9510
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		411	
	non noble metal	iron	7439-89-6	4.266	0.82		8226	
	non noble metal	copper	7440-50-8	173.237	33.40	34.27	334024	342764
wire	noble metal	gold	7440-57-5	0.291	0.06	0.06	561	561
encapsulation	organic material	carbon black	1333-86-4	1.303	0.25		2512	
	plastics	epoxy resin	-	37.777	7.28		72838	
	inorganic material	silicondioxide	60676-86-0	286.582	55.26	62.79	552566	627916
leadfinish	non noble metal	tin	7440-31-5	7.496	1.45	1.45	14453	14453
plating	noble metal	silver	7440-22-4	0.832	0.16	0.16	1604	1604
glue	plastics	epoxy resin	-	0.248	0.05		479	
	noble metal	silver	7440-22-4	1.407	0.27	0.32	2713	3192
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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